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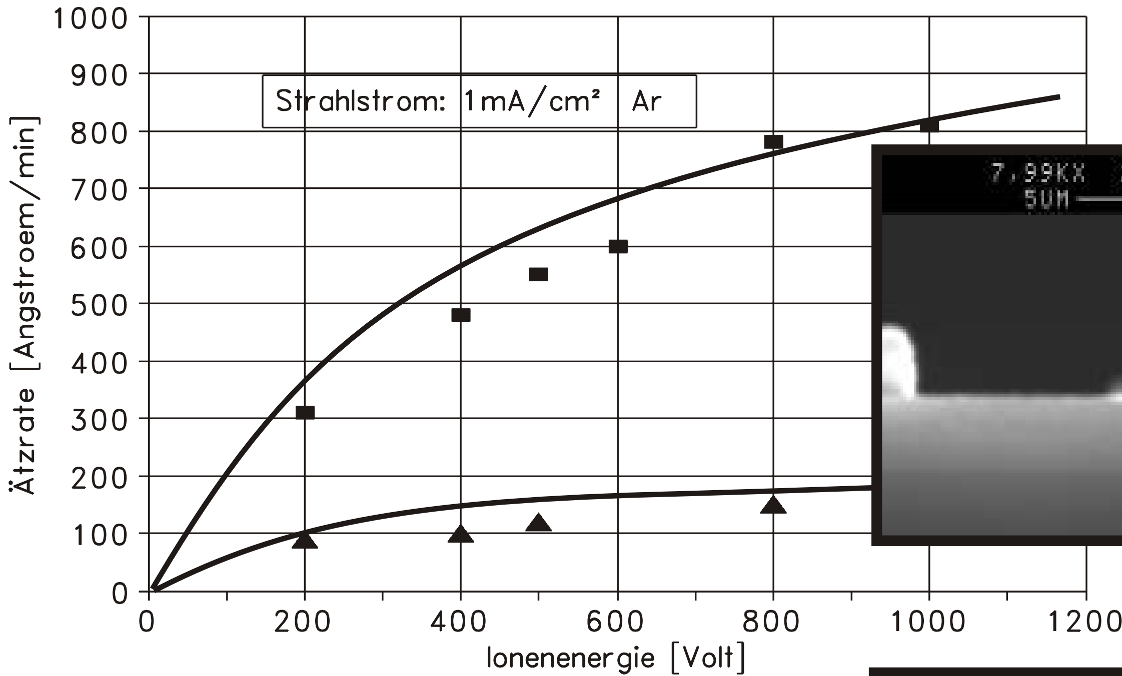
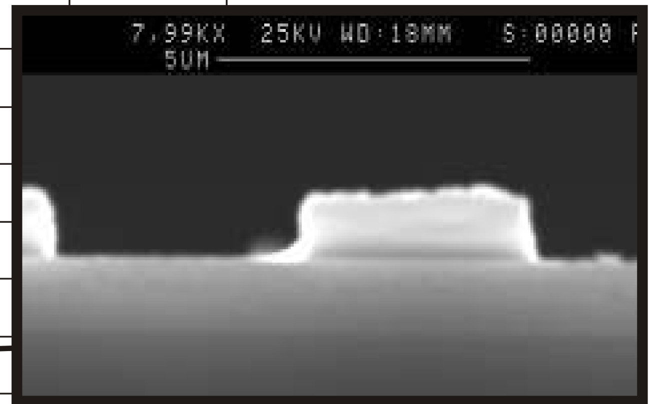
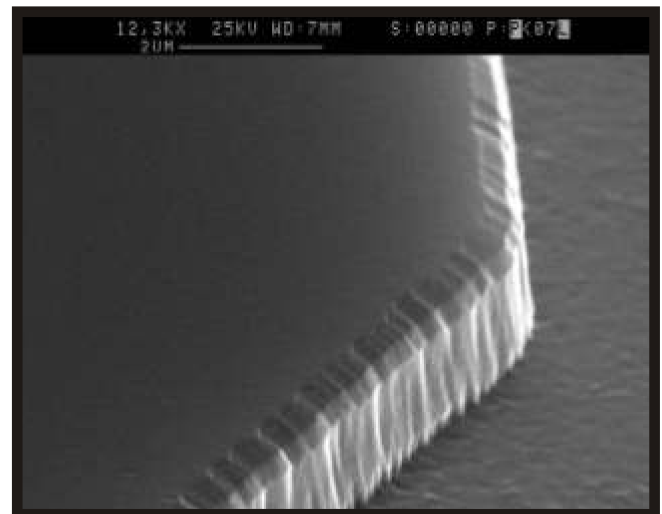
Ionfab Data

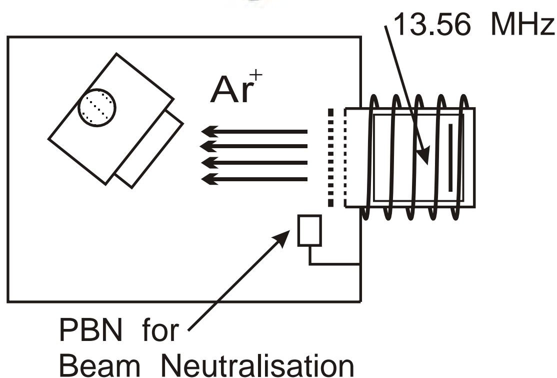
Ni, NiCr Ion Beam Etching







Ionfab 300 Plus



The SEMs show a 0.3 µm deep Ni etch with the PR mask not removed. With PR masks and Helium cooling the rate is ca 40 nm/ min at +/- 4 % uniformity.

The data are taken at normal incidence. However, for most applications we etch under an angle in order to avoid/ reduce redeposition at the side walls and "trenching".The max etch rate for NiCr depend on the vacuum and ist stochiometry.